Electronic Patent Application Fee Transmittal							
Application Number:	107	10711503					
Filing Date:	22-	22-Sep-2004					
Title of Invention:	IC PACKAGE HAVING GROUND IC CHIP AND METHOD OF MANUFACTURING SAME						
First Named Inventor/Applicant Name:	PEI-HAW TSAO						
Filer:	James H. Ortega/Angela Young						
Attorney Docket Number:	TSMC 2003-1622						
Filed as Large Entity							
Utility Filing Fees							
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)		
Basic Filing:							
Pages:							
Claims:							
Miscellaneous-Filing:							
Petition:							
Patent-Appeals-and-Interference:							
Post-Allowance-and-Post-Issuance:							
Extension-of-Time:							

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)				
Miscellaneous:								
Request for continued examination	1801	1	790	790				
	Tota	790						